[TO BE PUBLISHED IN THE GAZETTE OF INDIA, EXTRAORDINARY, PART II, SECTION 3, SUB-SECTION (i)]

GOVERNMENT OF INDIA MINISTRY OF FINANCE (DEPARTMENT OF REVENUE) Notification No. 21/2019 – Customs

New Delhi, the 6th July, 2019

G.S.R. ...(E).- In exercise of the powers conferred by sub-section (1) of section 25 of the Customs Act, 1962 (52 of 1962), the Central Government, on being satisfied that it is necessary in the public interest so to do, hereby makes the following further amendments in the notification of the Government of India, Ministry of Finance (Department of Revenue), No. 25/1998-Customs, dated the 2nd June, 1998, Published in the Gazette of India, Extraordinary, Part II, section 3, sub-section (i), vide G.S.R. 290(E), dated the 2nd June, 1998, namely:-

In the said notification, -

- (i) in the opening paragraph, for the words "sub-heading Nos.", the words "heading, sub-heading or tariff item" shall be substituted;
- (ii) for the TABLE, the following TABLE shall be substituted, namely: -

"TABLE

| S. No. | Heading or Sub- heading or tariff Item | Description |
|-----------|---|--|
| (1) | (2) | (3) |
| 1. | 7017 10 00 or 7020 00 | Quartz reactor tubes and holders designed for insertion into diffusion and oxidation furnaces for production of semi-conductor wafers. |
| 2. | 8419 89 or 8486 | Chemical vapour deposition apparatus for semi-conductor production. |
| 3. | 8419 90 or 8486 | Parts of chemical vapour deposition apparatus for semi-conductor production. |
| 4. | 8421 19 or 8486 | Spin dryers for semi-conductor wafer processing. |

| 5. | 8421 91 00 or 8486 | Parts of Spin dryers for semi-conductor wafer processing. |
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| 6. | 8424 89 or 8486 | Deflash machines for cleaning and removing contaminants from the metal leads of semiconductor packages prior to the electroplating process. |
| 7. | 8424 89 or 8486 | Spraying appliances for etching, stripping or cleaning semi- conductor wafers. |
| 8. | 8424 90 00 or 8486 | Parts of spraying appliances for etching, stripping or cleaning semi- conductor wafers. |
| 9. | 8456 11 00 or 8456 12 00 or 8486 | Machines for working any material by removal of material, by laser or other light or photo beam in the production of semiconductor wafers. |
| 10. | 8456 90 10 or 8486 | Machine tools for working any material by removal of material, by laser or other light or photon beam, ultrasonic, electro-discharge, electro-chemical, electron beam, ionic-beam or plasma arc processes, for dry-etching patterns on semiconductor materials of the said First Schedule. |
| 11. | 8486 40 00 | Focussed ion beam milling machines to produce or repair masks and reticles for patterns on semiconductor devices. |
| 12. | 8456 90 90 or 8486 | Laser cutters for cutting contacting tracks in semiconductor production by laser beam. |
| 13. | 8464 10 or 8486 | Machines for sawing monocrystal semiconductor boules into slices, or wafers into chips. |
| 14. | 8464 20 00 or 8486 | Grinding, polishing and lapping machines for processing of semiconductor wafers. |
| 15. | 8464 90 00 or 8486 | Dicing machines for scribing or scoring semiconductor wafers. |
| 16. | 8466 91 00 or 8486 | Parts of grinding, polishing and lapping machines for processing of semiconductor wafers. |
| 17. | 8466 91 00 or 8486 | Parts of machines for sawing monocrystal semiconductor boules into slices, or wafers into chips. |
| 18. | 8466 91 00 or 8486 | Parts of dicing machines for scribing or scoring semiconductor wafers. |
| 19. | 8466 93 or 8486 | Parts of focussed ion beam milling machines to produce or repair masks and reticles for patterns on semiconductor devices. |

| 20. | 8466 93 or 8486 | Parts of machines for working any material by removal of material, by laser or other light or photo beam in the production of semiconductor wafers. |
|-----|-------------------------------------|--|
| 21. | 8466 93 or 8486 | Parts of machines for dry-etching patterns on semiconductor materials. |
| 22. | 8466 93 or 8486 | Parts of laser cutters for cutting contacting tracks in semiconductor production by laser beam. |
| 23. | 8466 93 or 8486 | Parts of apparatus for stripping or cleaning semiconductor wafers. |
| 24. | 8477 10 00 or 8479 89 | Encapsulation equipment for assembly of semiconductors. |
| 25. | 8477 90 00 or 8479 90 | Parts of encapsulation equipment for assembly of semiconductors. |
| 26. | 8479 50 00 or 8486 | Automated machines for transport, handling and storage of semiconductor wafers, cassettes, wafer boxes and other material for semiconductor devices. |
| 27. | 8479 89 or 8486 | Apparatus for growing or pulling moriocrystal semiconductor boules. |
| 28. | 8479 89 or 8486 | Epitaxial deposition machines for semiconductor wafers. |
| 29. | 8479 89 or 8486 | Apparatus for physical deposition by sputtering on semiconductor wafers. |
| 30. | 8479 89 or 8543 30 00 or 8486 | Apparatus for wet-etching, developing, stripping or cleaning semiconductor wafers and flat panel displays. |
| 31. | 8479 89 or 8486 | Die attach apparatus, tape automated bonders and wire bonders for assembly of semiconductors. |
| 32. | 8479 89 or 8486 | Machines for bending, folding and straightening semiconductor leads. |
| 33. | 8479 89 or 8486 | Physical deposition apparatus for semiconductor production. |
| 34. | 8479 89 or 8486 | Spinners for coating photographic emulsions on semiconductor wafers. |
| 35. | 8479 90 or 8486 | Parts of apparatus for growing or pulling monocrystal semiconductor boules. |

| 36. | 8479 90 or 8486 | Parts of epitaxial deposition machines for semiconductor wafers. |
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| 37. | 8479 90 or 8486 | Parts of apparatus for physical deposition by sputtering on semiconductor wafers. |
| 38. | 8479 90 or 8486 | Parts for die attach apparatus, tape automated bonders and wire bonders for assembly of semiconductors. |
| 39. | 8479 90 or 8486 | Parts of spinners for coating photographic emulsions on semiconductor wafers. |
| 40. | 8479 90 or 8543 90 00 or 8486 | Parts of apparatus for wet-etching, developing, stripping or cleaning semiconductor wafers and flat panel displays. |
| 41. | 8479 90 or 8486 | Parts of automated machines for transport, handling and storage of semiconductor wafers, wafer cassettes, wafer boxes and other material for semiconductor devices. |
| 42. | 8479 90 or 8486 | Parts of machines for bending, folding and straightening semiconductor leads. |
| 43. | 8479 90 or 8486 | Parts of physical deposition apparatus for semiconductor production. |
| 44. | 8480 71 00 or 8486 | Injection and compression moulds for manufacture of semiconductor devices. |
| 45. | 8514 10 00 or 8486 | Resistance heated furnaces and ovens for the manufacture of semiconductor devices on semiconductor wafers. |
| 46. | 8514 20 00 or 8486 | Inductance or dielectric furnaces and ovens for the manufacture of semiconductor devices on semiconductor wafers. |
| 47. | 8514 30 or 8486 | Parts of resistance heated furnaces and ovens for the manufacture of semiconductor devices on semiconductor wafers. |
| 48. | 8514 30 or 8486 | Apparatus for rapid heating of semiconductor wafers. |
| 49. | 8514 90 00 or 8486 | Parts of furnaces and ovens of heading Nos. 8514 10 to 8514 30 or 8486. |
| 50. | 8514 90 00 or 8486 | Parts of apparatus for rapid heating of wafers. |
| 51. | 8543 10 10 or 8486 | Ion implanters for doping semiconductor materials. |

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| 65. | 9031 49 00 | Optical instruments and appliances for measuring surface particulate contamination on semiconductor wafers. |
|-----|-------------|---|
| 66. | 9031 90 00 | Parts and accessories of optical instruments and appliances for inspecting semiconductor wafers or devices or for inspecting masks, photomasks or reticles used in manufacturing semiconductor devices. |
| 67. | 9031 90 00 | Parts and accessories of optical instruments and appliances for measuring surface particulate contamination on semiconductor wafers. |
| 68. | Any Chapter | All goods required for the manufacture of goods specified against S.Nos. 1 to 67 above, subject to the condition that the importer follows the procedure set out in the Customs (Import of Goods at Concessional Rate of Duty) Rules, 2017.". |

[F. No. 334/3/2019-TRU]

(Gunjan Kumar Verma)

Under Secretary to the Government of India

Note: The principal notification No.25/98-Customs, dated the 2nd June, 1998 was published in the Gazette of India, Extraordinary, Part II, Section 3, Sub-section (i), *vide* number G.S.R.290(E), dated the 2nd June, 1998 and last amended, *vide*, notification No. 125/2006 -Customs, dated the 30th December, 2006, published, *vide* number G.S.R.786(E), dated the 30th December, 2006.